<table>
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<th>PCB VIEWED FROM TOP SIDE</th>
<th>BOARD #: TIDA-00795</th>
<th>REV: E1</th>
<th>SUN REV: Not In VersionControl</th>
</tr>
</thead>
<tbody>
<tr>
<td>TID #: TIDA-00795</td>
<td>GENERATED: 1/11/2016 9:38:23 AM</td>
<td>TEXAS INSTRUMENTS</td>
<td></td>
</tr>
</tbody>
</table>

 COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

Z1: Install label in silkscreen box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
Z2: These assemblies are ESD sensitive, ESD precautions shall be observed.
Z3: These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
Z4: These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
Components marked 'DIP' should not be populated.

Assembly Variant: 001

<table>
<thead>
<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #</th>
<th>TIDA-00795</th>
<th>REV: E1</th>
<th>SUN REV: Not In VersionControl</th>
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</thead>
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<tr>
<td></td>
<td>TIDA-00795</td>
<td>TEST INSTRUMENTS</td>
<td></td>
<td></td>
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</tbody>
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